



DATE: 18th July, 2019

PCN #: 2391 - REV 2

PCN Title: Clip Bond Structure, Lead Frame Type, and Mold Compound Changes to Enhance PowerDI-123 Package, as well as Qualification of Additional Wafer source for Select Products - Automotive

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2391 REV 2

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
18 th July, 2019	18 th October, 2019	Automotive Discrete Products	Assembly Materials	2391
TITLE				
Clip Bond Structure, Lead Frame Type, and Mold Compound Changes to Enhance PowerDI-123 Package, as well as Qualification of Additional Wafer source for Select Products				
DESCRIPTION OF CHANGE				
This PCN is being issued to notify customers that in order to improve PowerDI-123 package body strength and manufacturability, Diodes Incorporated has qualified an enhanced clip bond structure, new lead frame type and mold compound for the attached PowerDI-123 packaged automotive products.				
Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure that there is no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification / reliability report (embedded in this file).				
There will be no change to the Form, Fit, or Function of affected products.				
REV 2: In order to assure continuity of supply, Diodes Incorporated has qualified Phenitec Semiconductor in Okayama, Japan as an additional wafer source for all affected products except the DFLT33AQ-7 (as it was previously qualified with Phenitec die – marked with * in Affected Part list below). Refer to the attached revised qualification / reliability report for additional test results using Phenitec wafers.				
IMPACT				
No change in datasheet parameters and product performance				
PRODUCTS AFFECTED				
Please refer to the attached part list				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/pcns			
For More Information Contact:	http://www.diodes.com/contacts			
Data Sheet:	http://www.diodes.com/products			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Affected Part List					
DFLT33AQ-7*	DFLZ13Q-7	DFLZ20Q-7	DFLZ30Q-7	DFLZ5V1Q-7	DFLZ7V5Q-7
DFLZ10Q-7	DFLZ15Q-7	DFLZ22Q-7	DFLZ33Q-7	DFLZ5V6Q-7	DFLZ8V2Q-7
DFLZ11Q-7	DFLZ16Q-7	DFLZ24Q-7	DFLZ36Q-7	DFLZ6V2Q-7	DFLZ9V1Q-7
DFLZ12Q-7	DFLZ18Q-7	DFLZ27Q-7	DFLZ39Q-7	DFLZ6V8Q-7	